

**IN THE CLAIMS**

1-9 (cancelled)

10. (original) A method of manufacturing a thermally conductive substrate having a lead frame provided on one surface of an insulator sheet and a radiation plate provided on the other surface of the insulator sheet, a part of said lead frame extending to an end portion of said insulator sheet, the method comprising the steps of building up said lead frame on the one surface of said insulator sheet, building up the radiation plate on the other surface of said insulator sheet over an entire surface of the insulation sheet, and bonding said lead frame, said radiation plate and said insulator sheet to one another; up to a position away from the end portion of said insulator sheet inside of said insulator sheet in a plane direction of said insulator sheet, an end portion of the radiation plate located on and near an end portion of the insulator sheet, to which said lead frame extends, is removed.

11. (original) A method of manufacturing a thermally conductive substrate according to claim 10, wherein the end portion of said radiation plate is removed by cutting the end portion.

12. (original) A method of manufacturing a thermally conductive substrate according to claim 10, wherein the end portion of said radiation plate is removed by a photolithography step.

13. (original) A method of manufacturing a thermally conductive substrate according to claim 10 wherein a radiation plate having a split groove along a peripheral edge of a to-be-removed radiation plate region is prepared as said radiation plate; and after the radiation plate is bonded to said insulator sheet, the to-be-removed radiation plate region is divided from other radiation plate regions and removed along said split groove.

14. (original) A method of manufacturing a thermally conductive substrate having a lead frame provided on one surface of an insulator sheet and a radiation plate provided on the other surface of the insulator sheet, a part of said lead frame extending to an end portion of said insulator sheet, the method comprising the steps of: 5 preparing, as said radiation plate, a case-added radiation plate, an end portion of the radiation plate corresponding to and near the end portion of the insulator sheet, to which said lead frame extends, being removed in advance, a case surrounding an entire periphery of the radiation plate being arranged outside of the radiation plate, and building up said lead frame on the one surface of said insulator sheet and said case-added radiation plate on the other surface of the radiation plate to bond said lead frame, said insulator sheet and said case-added radiation plate to one another; and removing said case from said insulator sheet.

15. (cancelled)